Claims

1. A method for tacking of chips (4) onto a substrate (1) at chip positions (1c) which are distributed on a surface (1o) of the substrate (1) with the following steps, especially the following sequence:

- formation or application of a function layer (7) onto the substrate (1)

  a) which layer has been uncovered at the chip positions (1c) at least in the region of contacts (2) by structuring or

  b) by uncovering of a function layer (7) which has been uncovered on the surface (1o) at the chip positions (1c) at least in the region of the contacts (2) after formation or application of the function layer (7),

- tacking of chips (4) onto one chip contact side (7o) of the function layer (7) at the chip positions (1c) and contact-making of the contacts (2) via contact elements (3), wherein the ratio of (i) a distance between the contact elements (3) to (ii) a height difference between a lower surface of each chip (4) and the surface (1o) of the substrate (1) is between 3:1 and 1:2.

2. The method as claimed in Claim 1, wherein the function layer (7) is treated with a solvent on the chip contact side (7o), especially immediately before tacking, in order to induce an adhesion property which is necessary for tacking.

3. The method as claimed in one of the preceding claims, wherein the function layer (7) is provided with an adhesion layer on the chip contact side (7o).

4. The method as claimed in one of the preceding claims, wherein the uncovering comprises in addition an uncovering of an exposed area (1f) of the surface (1o) located outside the chip positions (1c).

5. The method as claimed in one of the preceding claims, wherein the uncovering additionally comprises a formation of channels (8) in the function layer (7), especially beginning from the

contacts (2), preferably ending on the exposed area (1f).

6. The method as claimed in one of the preceding claims, wherein the function layer (7) consists of a material which has low elasticity.

7. The method as claimed in one of the preceding claims, wherein the uncovering of the contacts (2) and/or the uncovering of the exposed area (1f) and/or the formation of the channels (8) takes place by photostructuring, especially with the following steps:

- exposure of the function layer (7) on the areas which are to be uncovered,
- lithography of the areas which are to be uncovered and
- stripping of the areas which are to be uncovered.

8. The method as claimed in one of the preceding claims, wherein when the contacts (2) are uncovered, through openings (9) are formed in the function layer (7), which openings extend as far as the contacts (2) and are arranged especially concentrically to the contacts (2), especially with a diameter D_1 greater than a diameter D_2 of the contact elements (3).

9. The method as claimed in one of the preceding claims, wherein the chips (4) are aligned with the contacts (2) before tacking.

10. The method as claimed in one of the preceding claims, wherein the chips (4) are bonded permanently to the function layer (7) after tacking.